

# Bill of Materials

**TI DESIGNS**  
**TIDA-00720**

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB	1		TIDA-00720	Any	Printed Circuit Board	
3	CIN, COUT	2	10uF	C1608X5R1A106M	TDK	CAP, CERM, 10 $\mu$ F, 10 V, +/-	0603
3	GNDIN, GNDOUT	2		6092	Keystone	Standard Banana Jack, Insulated, Black	6092
4	GND_EN_VIN	1		HTSW-103-07-G-S	Samtec	Header, 100mil, 3x1, Gold, TH	Header, 100mil, 3x1, TH
5	LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W
6	R1	1	15.0k	CRCW040215K0FKED	Vishay-Dale	RES, 15.0 k, 1%, 0.063 W,	0402
7	R2	1	12.4k	CRCW040212K4FKED	Vishay-Dale	RES, 12.4 k, 1%, 0.063 W,	0402
8	R3	1	100k	CRCW0402100KJNED	Vishay-Dale	RES, 100 k, 5%, 0.063 W, 0402	0402
9	S1	1		4-1437565-1	TE Connectivity	Switch, Tactile, SPST-NO,	SW, SPST 6x6 mm
10	SH-J1	1	1x2	SNT-100-BK-G	Samtec	Shunt, 100mil, Gold plated, Black	Shunt
11	TP1, TP2, TP3, TP4, TP5	5	Double	1573-2	Keystone	Terminal, Turret, TH, Double	Keystone1573-2
12	U1	1		LP38693SD-1.8	Texas Instruments	500mA Low Dropout CMOS	SDE06A
13	U2	1		TPL5111DDCR	Texas Instruments	Nano-power System Timer for Power Gating, DDC0006A	DDC0006A
14	VIN	1		6091	Keystone	Standard Banana Jack, Insulated, Red	6091
15	VOUT 3V3	1		108-0907-001	Emerson Network Power	BANANA JACK, 15A, Insulated, Nylon, Yellow	940x438x438mil
16	C1	0	0.1uF	C1005X5R0J104K	TDK	CAP, CERM, 0.1 $\mu$ F, 6.3 V, +/- 10%, X5R, 0402	0402
17	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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